

# SPECIFICATION

REFOND P/N

RF-A1E30-WYSE-A9B

R&D

Mass Production



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# 1. Description

## 1.1



The Yellow LED, which was fabricated by using a blue chip and the phosphor.  
 Product Package:3.2mmX3.0mmX0.6mm.

LED

3.2mmX3.0mmX0.6mm

## 1.2Features

EMC Package.EMC

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process. SMT

Available on tape and reel.

Moisture sensitivity level: Level 2. Level2

Compliance with RoHS and REACH. RoHS REACH

Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101  
 Stress Test Qualification for Automotive Grade Discrete Semicon ductors  
 AEC-Q101

## 1.3Application

Automotive Lighting Interior and Exterior.



## 1.4 Package Dimension

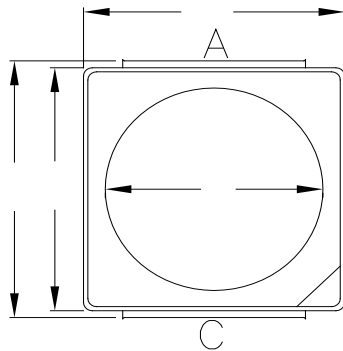


Fig.1-1 Top View

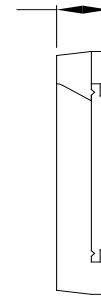


Fig.1-2 Side View

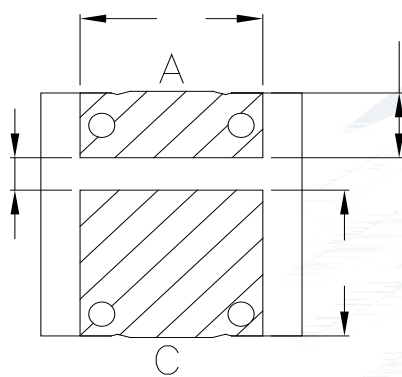


Fig.1-3 Bottom View

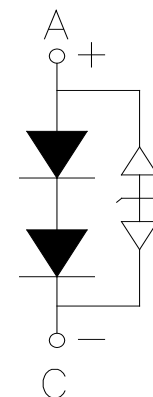


Fig.1-4 Polarity

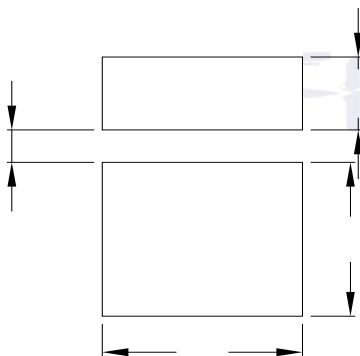


Fig.1-5 Soldering Patterns

### Notes

1. All dimensions units are millimeters.
2. All dimensions tolerances are  $\pm 0.2\text{mm}$  unless otherwise noted.



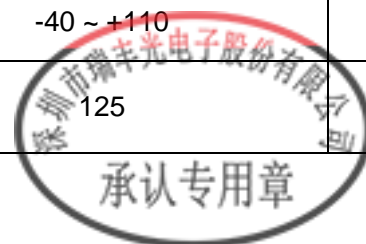
## 1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	$V_F$	$I_F=150\text{mA}$	5.4	---	6.6	V
Reverse Current	$I_R$	$V_R=5\text{V}$	---	---	10	$\mu\text{A}$
Luminous Flux		$I_F=150\text{mA}$	83.7	102	117	lm
Viewing Angle		$I_F=150\text{mA}$	---	120	---	deg
Thermal Resistance.	$R_{THJ-S}$	$I_F=150\text{mA}$	---	---	21	$^{\circ}\text{C}/\text{W}$

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	$P_D$	1320	mW
Forward Current	$I_F$	180	mA
Peak Forward Current	$I_{FP}$	350	mA
Reverse Voltage	$V_R$	5	V
Electrostatic Discharge (HBM)	$E_{SD}$	8000	V
Operating Temperature	$T_{OPR}$	-40 ~ +110	
Storage Temperature	$T_{STG}$	-40 ~ +110	
Junction Temperature	$T_J$	125	



Notes

1. 1/10 Duty cycle, 10ms pulse width.      10ms,      1/10.
2. The above forward voltage measurement allowance tolerance is  $\pm 0.1V$ .       $\pm 0.1V$ .
3. The above color coordinates measurement allowance tolerance is  $\pm 0.005$ .       $\pm 0.005$ .
4. The above luminous intensity measurement allowance tolerance  $\pm 10\%$ .       $\pm 10\%$ .
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED
8. ESD yield is over 90% at 8000V ESD (HBM). ESD protection during products handling is needed. 90% LED  
ESD8000V

## 1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=150mA)

### BIN (IF=150mA)

Table 1-3

V <sub>F</sub> V	Q2	R1	R2	S1	S2
	5.6-5.8	5.8-6.0	6.0-6.2	6.2-6.4	6.4-6.6
Im	RA	RB	SA		
	83.7-93.2	93.2-105	105-117		



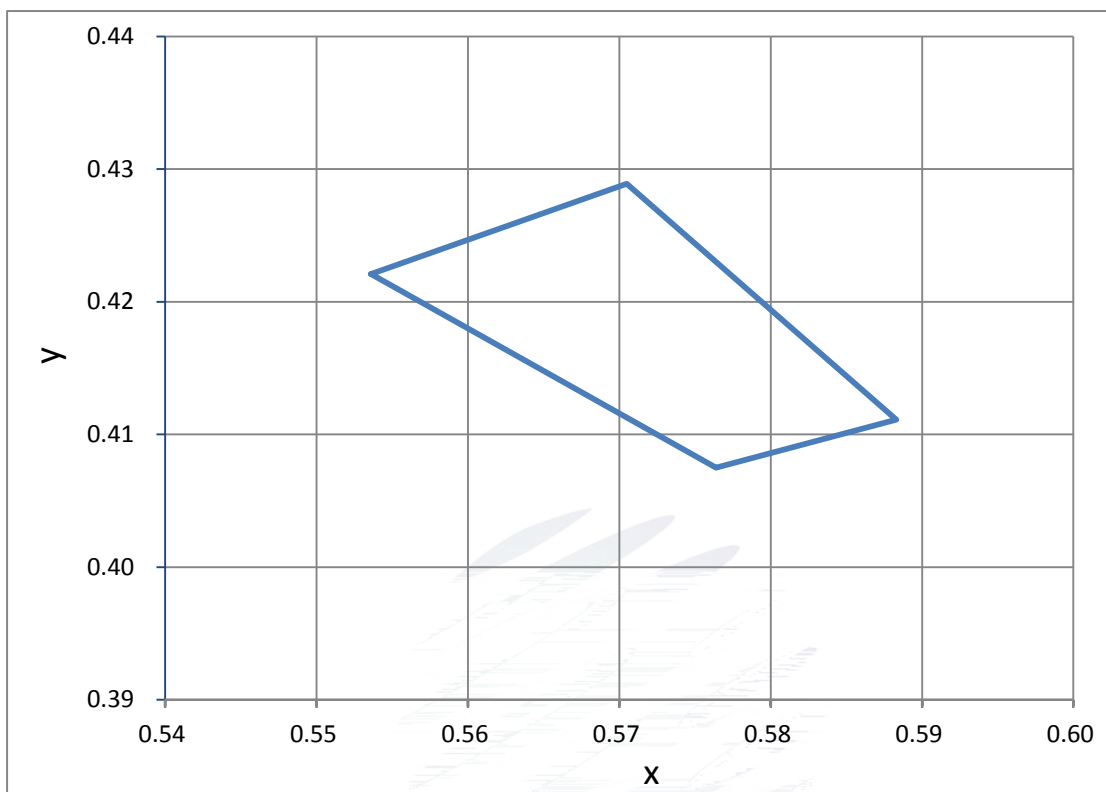


Fig. 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-4

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
5E	0.5536	0.4221	0.5764	0.4075	0.5883	0.4111	0.5705	0.4289



## 1.7 Typical Optical Characteristics Curves

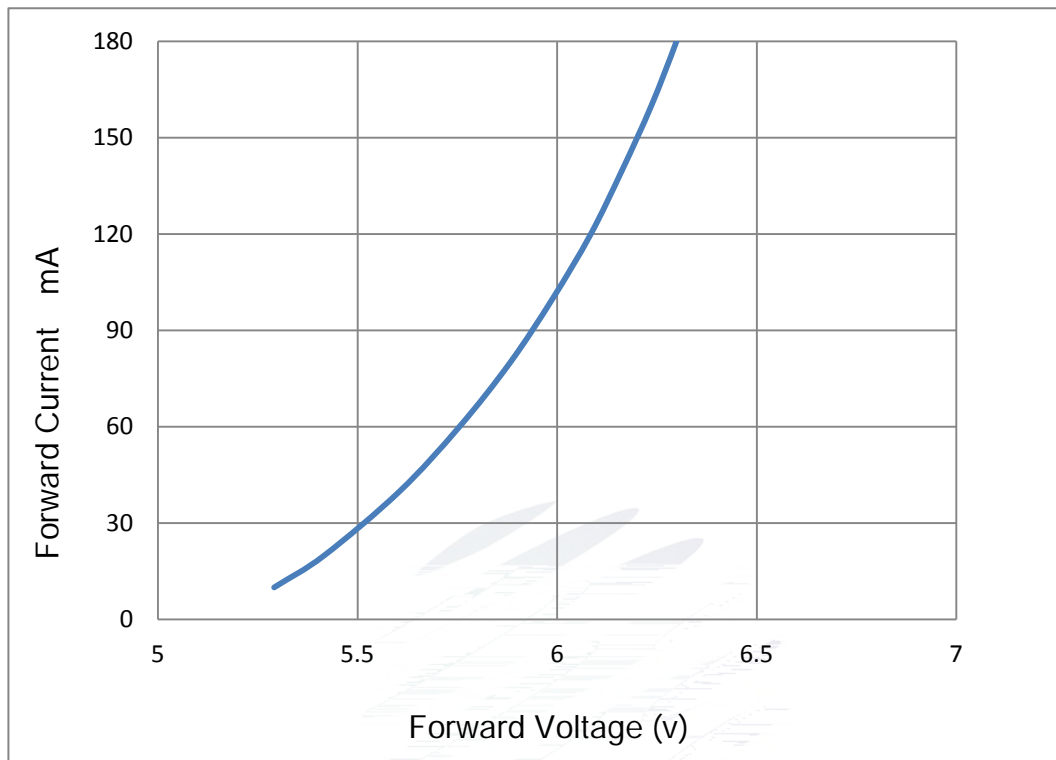


Fig. 1-7 Forward Voltage Vs Forward Current

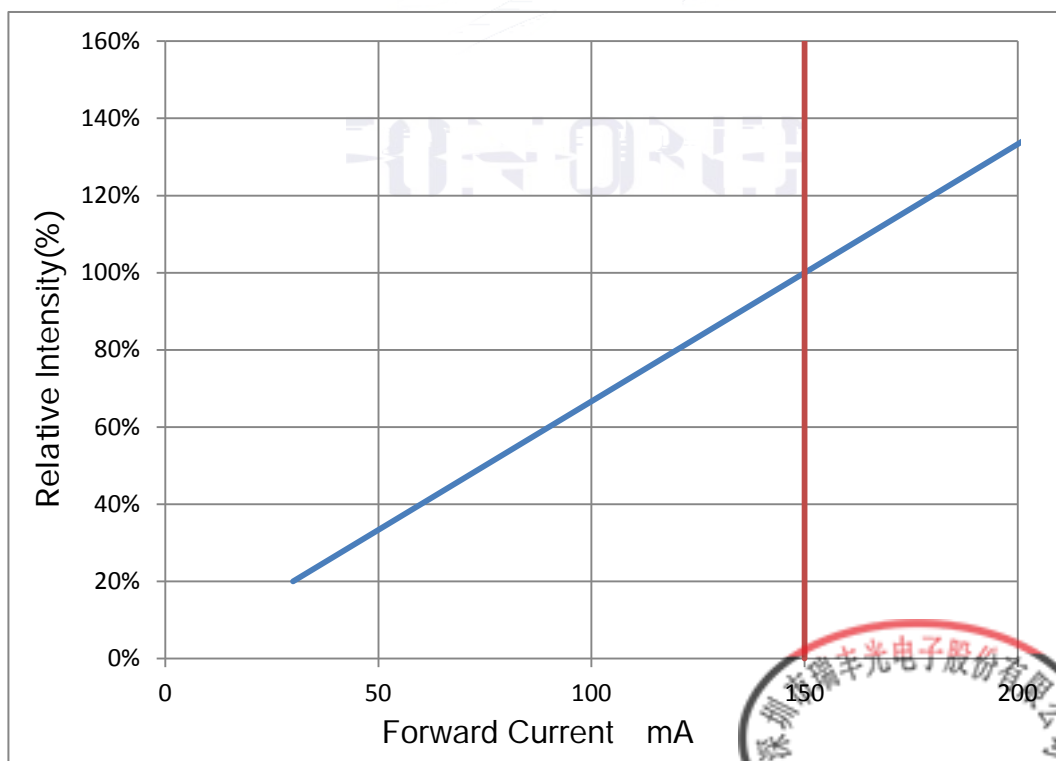
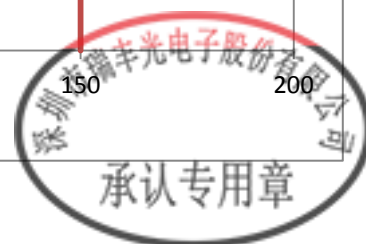


Fig. 1-8 Forward Current Vs Relative Intensity







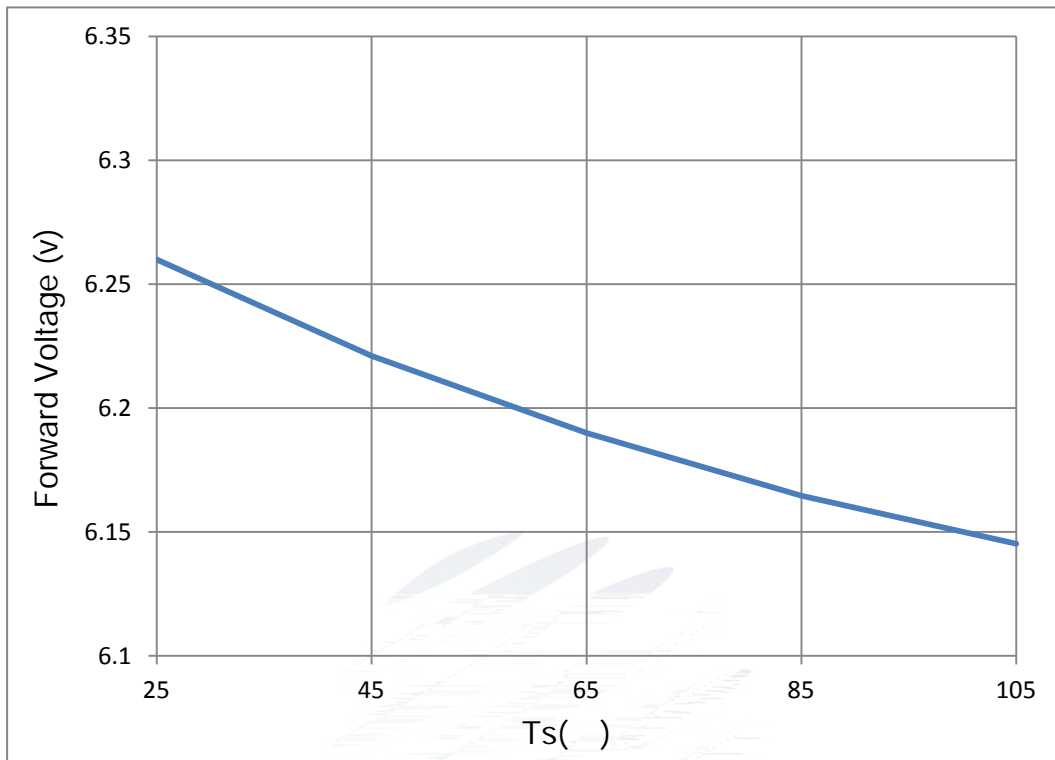


Fig. 1-11 Forward Voltage Vs Solder Temperature

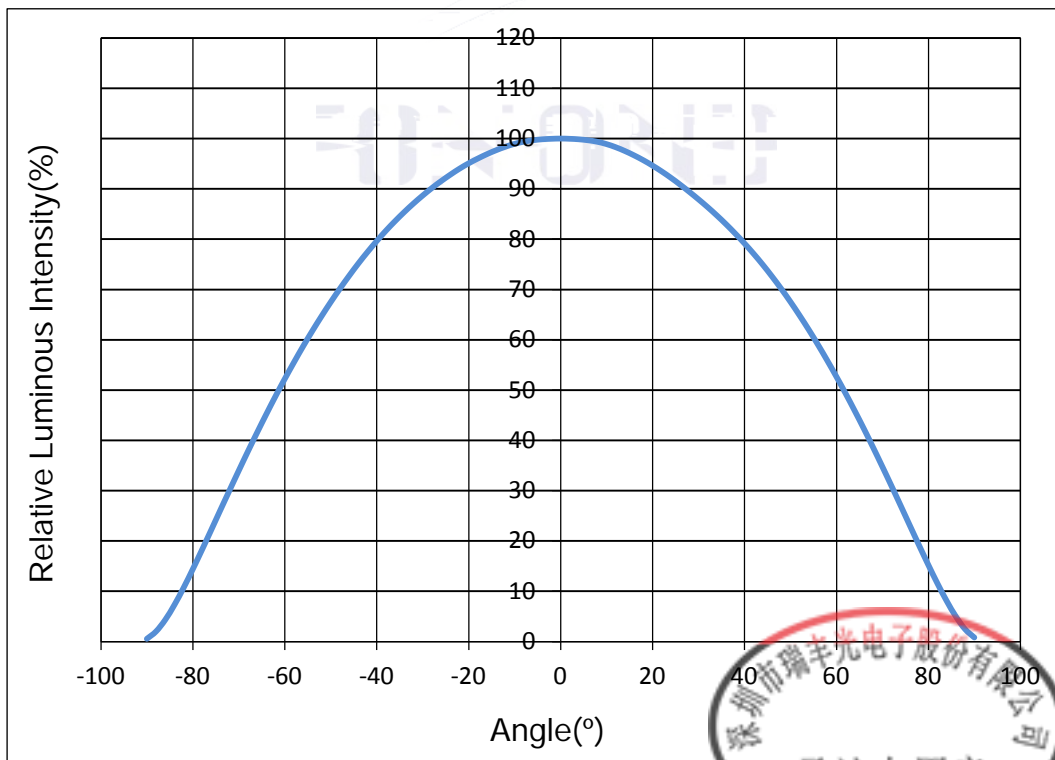
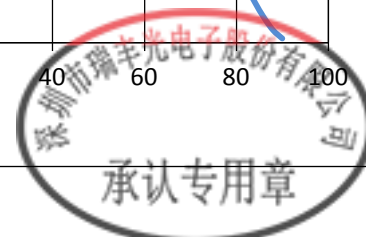


Fig. 1-12 Radiation diagram





## 2. Packaging

### 2.1 Packaging Specification

Package:4000pcs/reel.                      4000pcs

#### 2.1.1 Carrier Tape Dimension

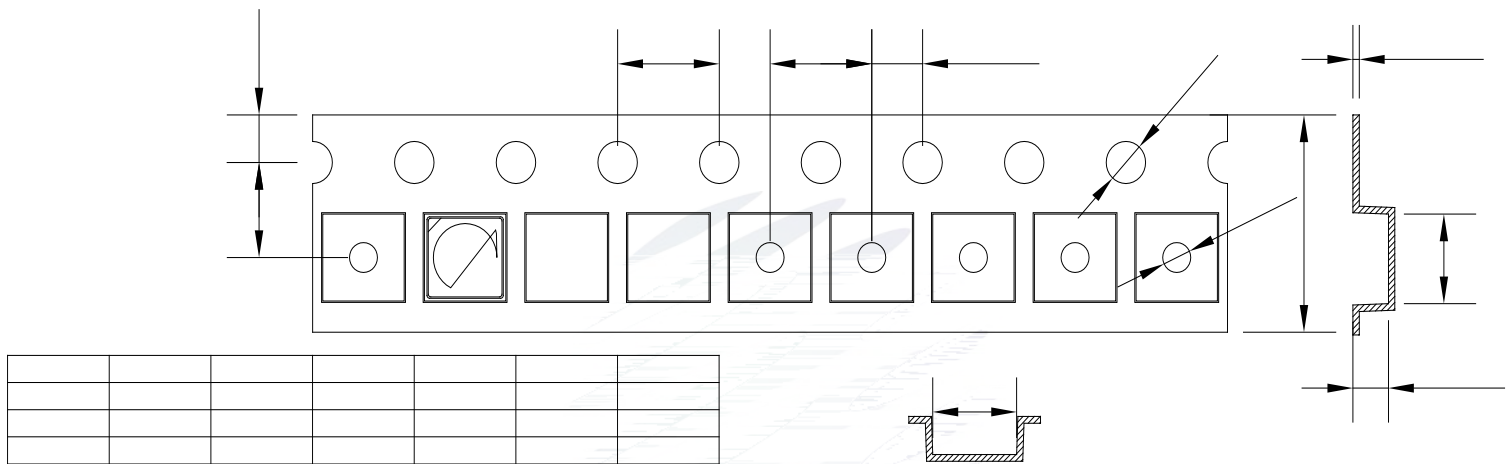


Fig.2-1 Carrier Tape Dimension

#### 2.1.2 Reel Dimension

Table 2-1 Reel Dimension

A	12±0.1mm
B	180±1mm
C	60±1mm
D	13.0±0.5mm

Fig.2-2 Reel Dimension

#### Notes

The tolerances unless mentioned ±0.1mm. Unit : mm

±0.1



### 2.1.3 Label Form Specification

Table 2-2 Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V <sub>F</sub>	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

Fig. 2-3 Label Form Specification

### 2.2 Moisture Resistant Packing

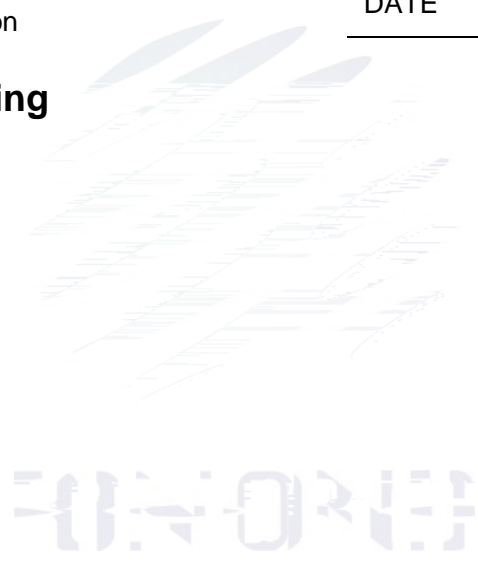


Fig.2-4 Moisture Resistant Packing

### 2.3 Cardboard Box

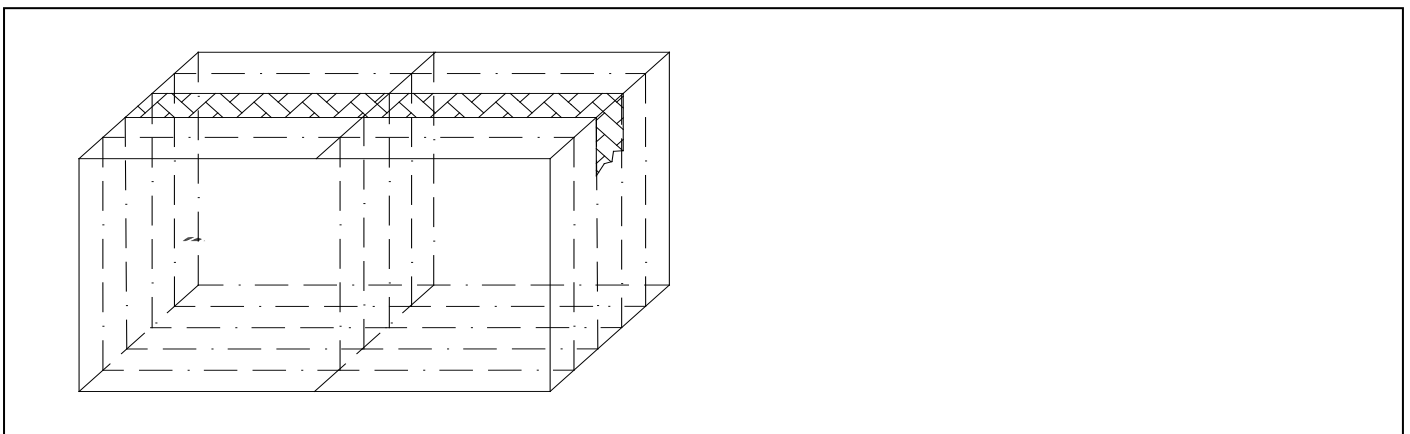


Fig.2-5 Cardboard Box

## 2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
MSL2 2	JESD22-A113	85 / 60%RH	168 hrs.	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min  125 15min	1000 cycle	20pcs.	0/1
Life Test	JESD22-A108	Ta=105 If=150mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%RH If=150mA	1000hrs.	20pcs.	0/1



## 2.5 Criteria For Judging Damage

Table 2-4Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	$V_F$	$I_F=150mA$	-	U.S.L*)x1.1
Reverse Current	$I_R$	$V_R = 5V$	-	U.S.L*)x2.0
Luminous Flux		$I_F=150mA$	L.S.L*)x0.7	-

### Notes

- 1.U.S.L: Upper standard level                      L.S.L: Lower standard level
- 2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. / LED  
LED
- 3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.



### 3. SMT Reflow Soldering Instructions SMT

#### 3.1 SMT Reflow Soldering Instructions SMT

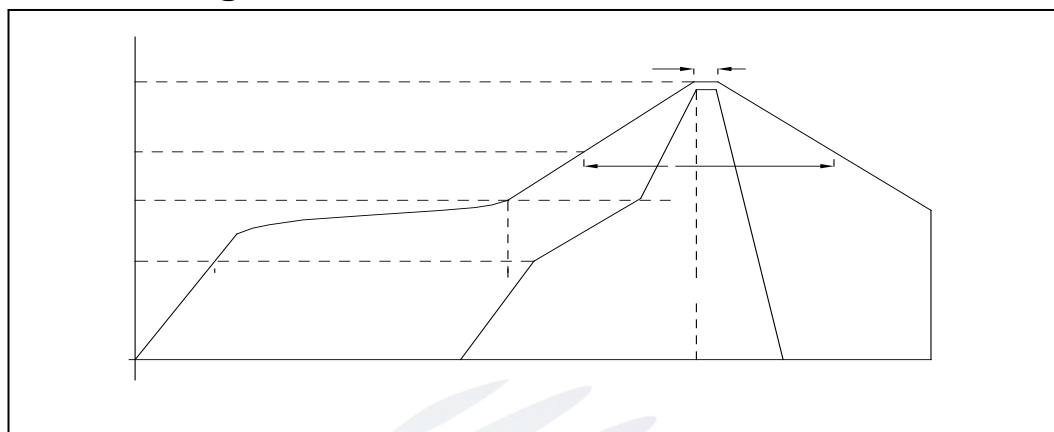


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Reflow parameters

Average temperature rise speed	$T_{sm}$	$T_p$	3 °C/	Max 3 °C/ s	
Preheating: minimum temperature	( $T_{sm}$ )		150 °C		
Preheating: Max temperature	( $T_{sm}$ )		200 °C		
Preheating: Time	$T_{sm}$	$T_{sm}$	60 - 120	60s-120s	
Time limited to maintain high temperature: the temperature	( $T_L$ )		217 °C		
Time limited to maintain high temperature: The Time	( $t_L$ )		60	Max 60s	
Peak /Classification of temperature:	/	( $T_p$ )	260 °C		
Time limit classification of peak temperature time		$t_p$	10	Max 10s	
	( $T_p$ )	5 °C	Hold time within	30	Max 30s
5 °C with the actual peak temperature ( $T_p$ )					
Cooling speed			6 °C/	Max 6 °C/ s	
25 °C		Needed time from 25 °C to $T_p$	8	Max 8 minutes	





## 4. Handling Precautions

### 4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.

LED 100PPM.

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

	LED	LED
	900PPM	900PPM
1500PPM.		

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor.

LED	LED	LED
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LED

(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.



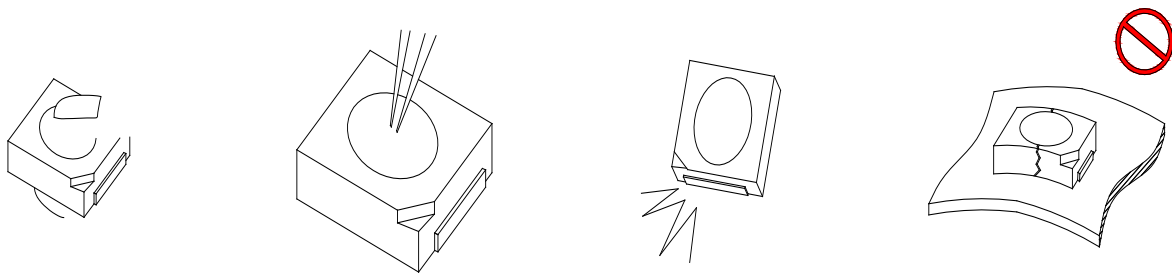


Fig 4-1 Cautions

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, other wise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design.

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED







Declare

This specification is written both in English and in Chinese and the latter is formal.